

MEMORIU ȘTIINȚIFIC

Drd. CĂLIN Mircea-Alexandru

Studii de doctorat

Perioada: 05.10.2020 – 01.05.2025

Conducător științific: Prof.dr.ing. Paul SVASTA

Domeniu: *Inginerie electronică, telecomunicații și tehnologii informaționale*

Titlul tezei de doctorat: *Contribuții privind dezvoltarea de antene pe substrat flexibil și sisteme de măsurare bazate pe radiofrecvență*

Activitate științifică

A.Lista de lucrări științifice:

1. M. Călin and P. Svasta, "Impedance matching for UHF band antennas on ceramic substrate", DESIGN AND TECHNOLOGY IN ELECTRONIC PACKAGING. IEEE INTERNATIONAL SYMPOSIUM, Nr 26, 2020, ISBN: 9781728175072
2. M. Călin and P. Svasta, "Wearable 2.4GHz Antenna on Textile Substrate", DESIGN AND TECHNOLOGY IN ELECTRONIC PACKAGING. IEEE INTERNATIONAL SYMPOSIUM, nr 27, 2021, ISBN: 9781665494472.
3. M. Călin and P. Svasta, "Wearable triple band WLAN antenna on leather belt", ELECTRONICS SYSTEM-INTEGRATION TECHNOLOGY CONFERENCE. IEEE. 2022. ISBN: 9781665461023
4. A. Bratu, M. Călin and P. Svasta, "Gesture Interaction with 3D Printed Hybrid Compression and Inertial Tracking Device Based on Plastic Embedded Antenna for Virtual Reality Integration", DESIGN AND TECHNOLOGY IN ELECTRONIC PACKAGING. IEEE INTERNATIONAL SYMPOSIUM. nr 28, 2022, ISBN: 9781665461023
5. M. Călin and P. Svasta, and B. Mihăilescu, "Textile and Plastic Materials Study for Radiofrequency Structure Fabrication", DESIGN AND TECHNOLOGY IN ELECTRONIC PACKAGING. IEEE INTERNATIONAL SYMPOSIUM, nr 29, 2023, ISBN: 9798350344127
6. M. Călin and P. Svasta, "Innovations in Electric Vehicle Supply Equipment: The Path Towards Smart Agriculture", DESIGN AND TECHNOLOGY IN ELECTRONIC PACKAGING. IEEE INTERNATIONAL SYMPOSIUM, nr 30, 2024, ISBN: 9798331539528.

B. Participări la conferințe/workshop-uri:

1. IEEE 26th International Symposium for Design and Technology in Electronic Packaging (SIITME), Pitesti, Romania, 2020
2. IEEE 27th International Symposium for Design and Technology in Electronic Packaging (SIITME), on-line, 2021
3. IEEE 29th Electronics System-Integration Technology Conference (ESTC), Sibiu, Romania, 2022
4. IEEE 28th International Symposium for Design and Technology in Electronic Packaging (SIITME), Bucharest, Romania, 2022
5. IEEE 29th International Symposium for Design and Technology in Electronic Packaging (SIITME), Craiova, Romania, 2023
6. IEEE 30th International Symposium for Design and Technology in Electronic Packaging (SIITME), Sibiu, Romania, 2024

C.Cursuri de perfecționare:

1. Introduction to Siwave and HFSS 2021, on-line, TENSOR SRL
2. Ansys HFSS 3D Workflow 2021, on-line, Aymen Mzoughi, Ansys Germany